

## Wafer Distribution Device Fanning & distribution device



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## Wafer Fanning Device

Wafer Fanning Device is used for separating and spreading cut wafer biscuits and feeding them to a chocolate coating plant.

The cut wafer biscuit move directly and automatically from the cutting machine to the wafer fanning device.

The fanning device spreads the wafer biscuits side to side with the required spacing. The fanning device is installed on a perforated stainless steel tables so that any wafer dust that falls during the process gets, eliminated in course of operation.

Once the wafer biscuits are distributed side to side, the conveyor carries the spread wafer biscuits forward and to the in feed mesh of the chocolate coating plant.



### TECHNICAL DATA:

Capacity	6-8 books per minute
Connected Load (KW)	0.37 rpm
Speed in RPM	95
Dimensions (mm)	
Length	2000
Width	1160
Height	900
Belt Width	995
Net.Weight (Kgs)	125
Shipping Volume (m3)	2.0 CBM

#### \*Modifications Reserved

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

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